8W
MHz CMOS Oscillator

Features

Frequency range : 4MHz to 125MHz
Compact and thin
SMD seam sealing ceramic package
Supply voltage : 1.8V ~ 3.3V
CMOS output
Tri-state function available
External dimensions (mm)
L : 2.5 x W : 2.0 x H : 0.8
RoHS compliant & Pb free

Applications

Mobile phone, Wearables
Networking, Server, Storage
Wireless communications
Fibre channel, Ethernet, SATA, SAS, PCI-E, USB, WLAN, BT
Notebook, HDD, SSD, Graphics card, Computer peripherals
Audio, Video, Gaming, DSC, IP CAM, Portable consumer products

Electrical Characteristics

Item	8W	Conditions
Frequency Range (F_0)	4MHz ~ 125MHz	
Frequency Stability (F_{stab})	±50ppm, ±25ppm	Note [1]
Operating Temperature Range (T_{OTR})	-40°C ~ +85°C	
Supply Voltage (V_{DD})	1.8V, 2.5V, 3.3V	V_{DD} ± 10%
Current Consumption (I_{DD})	10 mA Max.	
Output Type	CMOS	
Output Load (C_L)	15 pF	
Output Voltage High (V_{OH})	90% V_{DD} Min.	
Output Voltage Low (V_{OL})	10% V_{DD} Max.	
Rise & Fall Time (T_r / T_f)	5 ns Max.	10% ~ 90% of V_{DD}
Duty Cycle	45% ~ 55%	
Start-up Time	5 ms Max.	
Enable Voltage High, Logic "1"	70% V_{DD} Min.	Input to Pin1 Note [2]
Enable Voltage Low, Logic "0"	30% V_{DD} Max.	
Phase Jitter, RMS	1 ps Max.	Note [3]
Aging (F_{aging})	±3 ppm Max.	at 25°C±3°C,first year
Storage Temperature Range (T_{STR})	-55°C ~ +125°C	

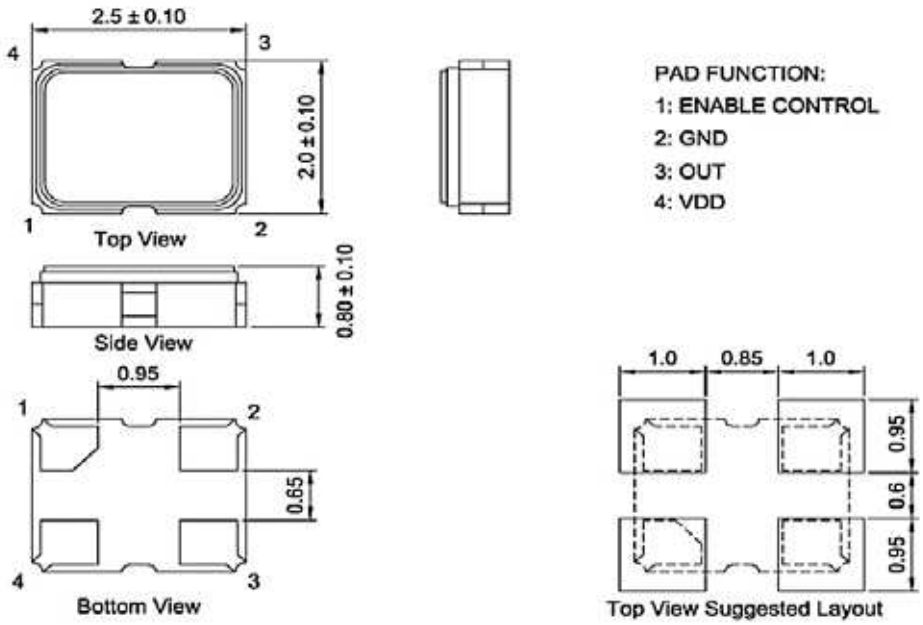
Notes:

[1] Inclusive of frequency tolerance at 25°C, 1st year aging at 25°C, and variations over operating temperature, supply voltage, and load.

[2] Output will be enable if Pin1 is Logic "1" or Open; Output will be disable if Pin1 is Logic "0".

[3] Freq. 10MHz~40MHz, integrated 12kHz~5MHz; Freq. >40MHz, integrated 12kHz~20MHz.

Dimensions



(Unit: mm)

Ordering Information

8W - 30.000M - B E - T

Frequency in Hz

Please contact us for available frequencies

Packaging Method

T	Tape & Reel

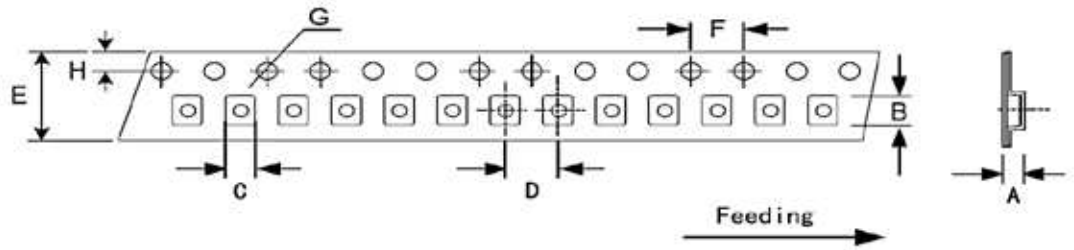
Supply Voltage

B	3.3 V
C	2.5 V
D	1.8 V

Frequency Stability

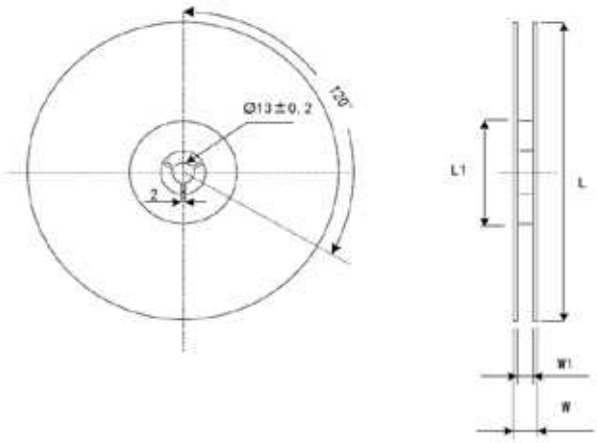
A	± 25 ppm (-10˚C ~ +70˚C)
D	± 25 ppm (-40˚C ~ +85˚C)
E	± 50 ppm (-40˚C ~ +85˚C)

Packing



DIMENSIONS	A	B	C	D	E	F	G	H
	1.15 ±0.05	2.70 ±0.05	2.25 ±0.05	4.00 ±0.10	8.00 ±0.20	4.00 ±0.10	1.55 ±0.05	1.75 ±0.10

(Unit: mm)



DIMENSIONS	L	L1	W	W1
	180 0/-3	60 +1/0	11.4 ±0.1	9 ±0.3

(Unit: mm)

Reflow Profile

Solder melting point : 220℃ ± 10℃, 60 sec. Min.
Peak temperature : 260℃ ± 10℃, 10 sec. Min.

